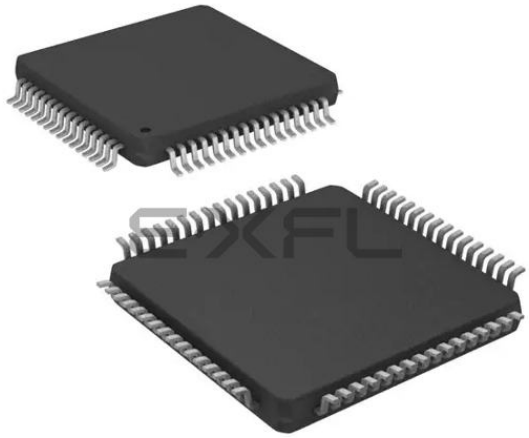

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	128KB (64K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f67j10-i-pt

TABLE 1-4: PIC18F8XJ10/8XJ15 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTF is a bidirectional I/O port.
RF1/AN6/C2OUT	23			
RF1		I/O	ST	Digital I/O.
AN6		I	Analog	Analog input 6.
C2OUT		O	—	Comparator 2 output.
RF2/AN7/C1OUT	18			
RF2		I/O	ST	Digital I/O.
AN7		I	Analog	Analog input 7.
C1OUT		O	—	Comparator 1 output.
RF3/AN8	17			
RF3		I/O	ST	Digital I/O.
AN8		I	Analog	Analog input 8.
RF4/AN9	16			
RF4		I/O	ST	Digital I/O.
AN9		I	Analog	Analog input 9.
RF5/AN10/CVREF	15			
RF5		I/O	ST	Digital I/O.
AN10		I	Analog	Analog input 10.
CVREF		O	—	Comparator reference voltage output.
RF6/AN11	14			
RF6		I/O	ST	Digital I/O.
AN11		I	Analog	Analog input 11.
RF7/$\overline{SS1}$	13			
RF7		I/O	ST	Digital I/O.
$\overline{SS1}$		I	TTL	SPI slave select input.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I = Input; O = Output; P = Power; OD = Open-Drain (no P diode to VDD); I^2C/SMB = I^2C™/SMBus input buffer

Note 1: Alternate assignment for ECCP2/P2A when Configuration bit, CCP2MX, is cleared (Extended Microcontroller mode).

2: Default assignment for ECCP2/P2A for all devices in all operating modes (CCP2MX is set).

3: Default assignments for P1B/P1C/P3B/P3C (ECCPMX Configuration bit is set).

4: Alternate assignment for ECCP2/P2A when CCP2MX is cleared (Microcontroller mode).

5: Alternate assignments for P1B/P1C/P3B/P3C (ECCPMX Configuration bit is cleared).

3.7 Effects of Power-Managed Modes on the Various Clock Sources

When PRI_IDLE mode is selected, the designated primary oscillator continues to run without interruption. For all other power-managed modes, the oscillator using the OSC1 pin is disabled. The OSC1 pin (and OSC2 pin if used by the oscillator) will stop oscillating.

In secondary clock modes (SEC_RUN and SEC_IDLE), the Timer1 oscillator is operating and providing the device clock. The Timer1 oscillator may also run in all power-managed modes if required to clock Timer1 or Timer3.

In RC_RUN and RC_IDLE modes, the internal oscillator provides the device clock source. The 31 kHz INTRC output can be used directly to provide the clock and may be enabled to support various special features, regardless of the power-managed mode (see **Section 24.2 "Watchdog Timer (WDT)"** through **Section 24.5 "Fail-Safe Clock Monitor"** for more information on WDT, Fail-Safe Clock Monitor and Two-Speed Start-up).

If the Sleep mode is selected, all clock sources are stopped. Since all the transistor switching currents have been stopped, Sleep mode achieves the lowest current consumption of the device (only leakage currents).

Enabling any on-chip feature that will operate during Sleep will increase the current consumed during Sleep. The INTRC is required to support WDT operation. The Timer1 oscillator may be operating to support a Real-Time Clock. Other features may be operating that do not require a device clock source (i.e., MSSP slave, PSP, INTx pins and others). Peripherals that may add significant current consumption are listed in **Section 27.2 "DC Characteristics: Power-Down and Supply Current"**.

3.8 Power-up Delays

Power-up delays are controlled by two timers, so that no external Reset circuitry is required for most applications. The delays ensure that the device is kept in Reset until the device power supply is stable under normal circumstances and the primary clock is operating and stable. For additional information on power-up delays, see **Section 5.5 "Power-up Timer (PWRT)"**.

The first timer is the Power-up Timer (PWRT), which provides a fixed delay on power-up (parameter 33, Table 27-12). It is always enabled.

The second timer is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable (HS modes). The OST does this by counting 1024 oscillator cycles before allowing the oscillator to clock the device.

There is a delay of interval, TCSD (parameter 38, Table 27-12), following POR, while the controller becomes ready to execute instructions.

TABLE 3-3: OSC1 AND OSC2 PIN STATES IN SLEEP MODE

Oscillator Mode	OSC1 Pin	OSC2 Pin
EC, ECPLL	Floating, pulled by external clock	At logic low (clock/4 output)
HS, HSPLL	Feedback inverter disabled at quiescent voltage level	Feedback inverter disabled at quiescent voltage level

Note: See Table 5-2 in **Section 5.0 "Reset"** for time-outs due to Sleep and $\overline{\text{MCLR}}$ Reset.

5.2 Master Clear ($\overline{MCLR}$)

The $\overline{MCLR}$ pin provides a method for triggering a hard external Reset of the device. A Reset is generated by holding the pin low. PIC18 extended microcontroller devices have a noise filter in the $\overline{MCLR}$ Reset path which detects and ignores small pulses.

The $\overline{MCLR}$ pin is not driven low by any internal Resets, including the WDT.

5.3 Power-on Reset (POR)

A Power-on Reset condition is generated on-chip whenever VDD rises above a certain threshold. This allows the device to start in the initialized state when VDD is adequate for operation.

To take advantage of the POR circuitry, tie the $\overline{MCLR}$ pin through a resistor (1 kΩ to 10 kΩ) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset delay. A minimum rise rate for VDD is specified (parameter D004). For a slow rise time, see Figure 5-2.

When the device starts normal operation (i.e., exits the Reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

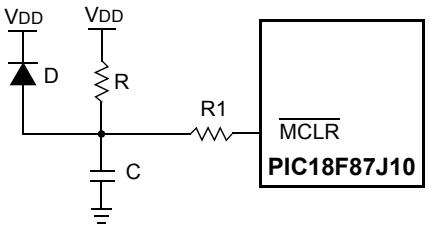
POR events are captured by the $\overline{POR}$ bit (RCON<1>). The state of the bit is set to '0' whenever a POR occurs; it does not change for any other Reset event. POR is not reset to '1' by any hardware event. To capture multiple events, the user manually resets the bit to '1' in software following any POR.

5.4 Brown-out Reset (BOR)

The PIC18F87J10 family of devices incorporate a simple BOR function when the internal regulator is enabled (ENVREG pin is tied to VDD). Any drop of VDD below VBOR (parameter D005) for greater than time TBOR (parameter 35) will reset the device. A Reset may or may not occur if VDD falls below VBOR for less than TBOR. The chip will remain in Brown-out Reset until VDD rises above VBOR.

Once a BOR has occurred, the Power-up Timer will keep the chip in Reset for TPWRT (parameter 33). If VDD drops below VBOR while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above VBOR, the Power-up Timer will execute the additional time delay.

FIGURE 5-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if the VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that the voltage drop across R does not violate the device's electrical specification.

3: R1 ≥ 1 kΩ will limit any current flowing into $\overline{MCLR}$ from external capacitor C, in the event of $\overline{MCLR}$/VPP pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

5.4.1 DETECTING BOR

The $\overline{BOR}$ bit always resets to '0' on any BOR or POR event. This makes it difficult to determine if a $\overline{BOR}$ event has occurred just by reading the state of $\overline{BOR}$ alone. A more reliable method is to simultaneously check the state of both $\overline{POR}$ and $\overline{BOR}$. This assumes that the $\overline{POR}$ bit is reset to '1' in software immediately after any POR event. If $\overline{BOR}$ is '0' while $\overline{POR}$ is '1', it can be reliably assumed that a BOR event has occurred.

If the voltage regulator is disabled, Brown-out Reset functionality is disabled. In this case, the $\overline{BOR}$ bit cannot be used to determine a BOR event. The $\overline{BOR}$ bit is still cleared by a POR event.

TABLE 5-2: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices		Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets WDT Reset RESET Instruction Stack Resets	Wake-up via WDT or Interrupt
INDF2	PIC18F6XJ1X	PIC18F8XJ1X	N/A	N/A	N/A
POSTINC2	PIC18F6XJ1X	PIC18F8XJ1X	N/A	N/A	N/A
POSTDEC2	PIC18F6XJ1X	PIC18F8XJ1X	N/A	N/A	N/A
PREINC2	PIC18F6XJ1X	PIC18F8XJ1X	N/A	N/A	N/A
PLUSW2	PIC18F6XJ1X	PIC18F8XJ1X	N/A	N/A	N/A
FSR2H	PIC18F6XJ1X	PIC18F8XJ1X	---- xxxx	---- uuuu	---- uuuu
FSR2L	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
STATUS	PIC18F6XJ1X	PIC18F8XJ1X	---x xxxx	---u uuuu	---u uuuu
TMR0H	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
TMR0L	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
T0CON	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	uuuu uuuu
OSCCON	PIC18F6XJ1X	PIC18F8XJ1X	0--- q-00	0--- q-00	u--- q-uu
WDTCON	PIC18F6XJ1X	PIC18F8XJ1X	---- ---0	---- ---0	---- ---u
RCON(4)	PIC18F6XJ1X	PIC18F8XJ1X	0--1 1100	0--q qquu	u--u qquu
TMR1H	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1L	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	u0uu uuuu	uuuu uuuu
TMR2	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
PR2	PIC18F6XJ1X	PIC18F8XJ1X	1111 1111	1111 1111	1111 1111
T2CON	PIC18F6XJ1X	PIC18F8XJ1X	-000 0000	-000 0000	-uuu uuuu
SSP1BUF	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
SSP1ADD	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
SSP1STAT	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
SSP1CON1	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
SSP1CON2	PIC18F6XJ1X	PIC18F8XJ1X	0000 0000	0000 0000	uuuu uuuu
ADRESH	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADRESL	PIC18F6XJ1X	PIC18F8XJ1X	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	PIC18F6XJ1X	PIC18F8XJ1X	0-00 0000	0-00 0000	u-uu uuuu
ADCON1	PIC18F6XJ1X	PIC18F8XJ1X	--00 0000	--00 0000	--uu uuuu
ADCON2	PIC18F6XJ1X	PIC18F8XJ1X	0-00 0000	0-00 0000	u-uu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.

Note 1: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).

4: See Table 5-1 for Reset value for specific condition.

6.2 PIC18 Instruction Cycle

6.2.1 CLOCKING SCHEME

The microcontroller clock input, whether from an internal or external source, is internally divided by four to generate four non-overlapping quadrature clocks (Q1, Q2, Q3 and Q4). Internally, the program counter is incremented on every Q1; the instruction is fetched from the program memory and latched into the instruction register during Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 6-5.

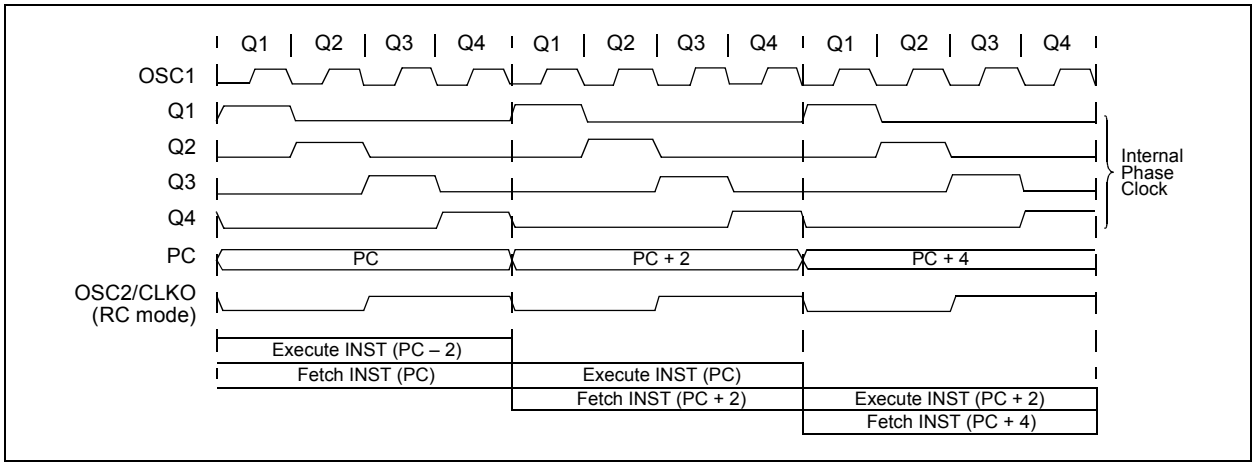
6.2.2 INSTRUCTION FLOW/PIPELINING

An “Instruction Cycle” consists of four Q cycles, Q1 through Q4. The instruction fetch and execute are pipelined in such a manner that a fetch takes one instruction cycle, while the decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., `GOTO`), then two cycles are required to complete the instruction (Example 6-3).

A fetch cycle begins with the Program Counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the Instruction Register (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 6-5: CLOCK/INSTRUCTION CYCLE



EXAMPLE 6-3: INSTRUCTION PIPELINE FLOW

	TCY0	TCY1	TCY2	TCY3	TCY4	TCY5
1. MOVLW 55h	Fetch 1	Execute 1				
2. MOVWF PORTB		Fetch 2	Execute 2			
3. BRA SUB_1			Fetch 3	Execute 3		
4. BSF PORTA, BIT3 (Forced NOP)				Fetch 4	Flush (NOP)	
5. Instruction @ address SUB_1					Fetch SUB_1	Execute SUB_1

All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is “flushed” from the pipeline while the new instruction is being fetched and then executed.

REGISTER 10-8: PIE2: PERIPHERAL INTERRUPT ENABLE REGISTER 2

R/W-0	R/W-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0
OSCFIE	CMIE	—	—	BCL1IE	—	TMR3IE	CCP2IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **OSCFIE:** Oscillator Fail Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 6 **CMIE:** Comparator Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 5-4 **Unimplemented:** Read as '0'

bit 3 **BCL1IE:** Bus Collision Interrupt Enable bit (MSSP1 module)
1 = Enabled
0 = Disabled

bit 2 **Unimplemented:** Read as '0'

bit 1 **TMR3IE:** TMR3 Overflow Interrupt Enable bit
1 = Enabled
0 = Disabled

bit 0 **CCP2IE:** ECCP2 Interrupt Enable bit
1 = Enabled
0 = Disabled

TABLE 11-7: PORTC FUNCTIONS

Pin Name	Function	TRIS Setting	I/O	I/O Type	Description
RC0/T1OSO/ T13CKI	RC0	0	O	DIG	LATC<0> data output.
		1	I	ST	PORTC<0> data input.
	T1OSO	x	O	ANA	Timer1 oscillator output; enabled when Timer1 oscillator enabled. Disables digital I/O.
	T13CKI	1	I	ST	Timer1/Timer3 counter input.
RC1/T1OSI/ ECCP2/P2A	RC1	0	O	DIG	LATC<1> data output.
		1	I	ST	PORTC<1> data input.
	T1OSI	x	I	ANA	Timer1 oscillator input; enabled when Timer1 oscillator enabled. Disables digital I/O.
	ECCP2(1)	0	O	DIG	CCP2 compare output and CCP2 PWM output; takes priority over port data.
		1	I	ST	CCP2 capture input.
	P2A(1)	0	O	DIG	ECCP2 Enhanced PWM output, Channel A. May be configured for tri-state during Enhanced PWM shutdown events. Takes priority over port data.
RC2/ECCP1/ P1A	RC2	0	O	DIG	LATC<2> data output.
		1	I	ST	PORTC<2> data input.
	ECCP1	0	O	DIG	CCP1 compare output and CCP1 PWM output; takes priority over port data.
		1	I	ST	CCP1 capture input.
	P1A	0	O	DIG	ECCP1 Enhanced PWM output, Channel A. May be configured for tri-state during Enhanced PWM shutdown events. Takes priority over port data.
RC3/SCK1/ SCL1	RC3	0	O	DIG	LATC<3> data output.
		1	I	ST	PORTC<3> data input.
	SCK1	0	O	DIG	SPI clock output (MSSP1 module); takes priority over port data.
		1	I	ST	SPI clock input (MSSP1 module).
	SCL1	0	O	DIG	I^2C™ clock output (MSSP1 module); takes priority over port data.
		1	I	I^2C/SMB	I^2C clock input (MSSP1 module); input type depends on module setting.
RC4/SDI1/ SDA1	RC4	0	O	DIG	LATC<4> data output.
		1	I	ST	PORTC<4> data input.
	SDI1	1	I	ST	SPI data input (MSSP1 module).
	SDA1	1	O	DIG	I^2C data output (MSSP1 module); takes priority over port data.
		1	I	I^2C/SMB	I^2C data input (MSSP1 module); input type depends on module setting.
RC5/SDO1	RC5	0	O	DIG	LATC<5> data output.
		1	I	ST	PORTC<5> data input.
	SDO1	0	O	DIG	SPI data output (MSSP1 module); takes priority over port data.
RC6/TX1/CK1	RC6	0	O	DIG	LATC<6> data output.
		1	I	ST	PORTC<6> data input.
	TX1	1	O	DIG	Synchronous serial data output (EUSART1 module); takes priority over port data.
	CK1	1	O	DIG	Synchronous serial data input (EUSART1 module). User must configure as an input.
		1	I	ST	Synchronous serial clock input (EUSART1 module).
RC7/RX1/DT1	RC7	0	O	DIG	LATC<7> data output.
		1	I	ST	PORTC<7> data input.
	RX1	1	I	ST	Asynchronous serial receive data input (EUSART1 module).
	DT1	1	O	DIG	Synchronous serial data output (EUSART1 module); takes priority over port data.
		1	I	ST	Synchronous serial data input (EUSART1 module). User must configure as an input.

Legend: PWR = Power Supply, O = Output, I = Input, I^2C™/SMB = I^2C/SMBus input buffer, ANA = Analog Signal, DIG = Digital Output, ST = Schmitt Buffer Input, TTL = TTL Buffer Input, x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

Note 1: Default assignment for ECCP2/P2A when the CCP2MX Configuration bit is set.

TABLE 11-11: PORTE FUNCTIONS

Pin Name	Function	TRIS Setting	I/O	I/O Type	Description
RE0/AD8/$\overline{RD}$/ P2D	RE0	0	O	DIG	LATE<0> data output.
		1	I	ST	PORTE<0> data input.
	AD8(3)	x	O	DIG	External memory interface, address/data bit 8 output.(2)
		x	I	TTL	External memory interface, data bit 8 input.(2)
	$\overline{RD}$	1	I	TTL	Parallel Slave Port read enable control input.
	P2D	0	O	DIG	ECCP2 Enhanced PWM output, Channel D; takes priority over port and PSP data. May be configured for tri-state during Enhanced PWM shutdown events.
RE1/AD9/$\overline{WR}$/ P2C	RE1	0	O	DIG	LATE<1> data output.
		1	I	ST	PORTE<1> data input.
	AD9(3)	x	O	DIG	External memory interface, address/data bit 9 output.(2)
		x	I	TTL	External memory interface, data bit 9 input.(2)
	$\overline{WR}$	1	I	TTL	Parallel Slave Port write enable control input.
	P2C	0	O	DIG	ECCP2 Enhanced PWM output, Channel C; takes priority over port and PSP data. May be configured for tri-state during Enhanced PWM shutdown events.
RE2/AD10/$\overline{CS}$/ P2B	RE2	0	O	DIG	LATE<2> data output.
		1	I	ST	PORTE<2> data input.
	AD10(3)	x	O	DIG	External memory interface, address/data bit 10 output.(2)
		x	I	TTL	External memory interface, data bit 10 input.(2)
	$\overline{CS}$	1	I	TTL	Parallel Slave Port chip select control input.
	P2B	0	O	DIG	ECCP2 Enhanced PWM output, Channel B; takes priority over port and PSP data. May be configured for tri-state during Enhanced PWM shutdown events.
RE3/AD11/ P3C	RE3	0	O	DIG	LATE<3> data output.
		1	I	ST	PORTE<3> data input.
	AD11(3)	x	O	DIG	External memory interface, address/data bit 11 output.(2)
		x	I	TTL	External memory interface, data bit 11 input.(2)
	P3C(1)	0	O	DIG	ECCP3 Enhanced PWM output, Channel C; takes priority over port and PSP data. May be configured for tri-state during Enhanced PWM shutdown events.
RE4/AD12/ P3B	RE4	0	O	DIG	LATE<4> data output.
		1	I	ST	PORTE<4> data input.
	AD12(3)	x	O	DIG	External memory interface, address/data bit 12 output.(2)
		x	I	TTL	External memory interface, data bit 12 input.(2)
	P3B(1)	0	O	DIG	ECCP3 Enhanced PWM output, Channel B; takes priority over port and PSP data. May be configured for tri-state during Enhanced PWM shutdown events.
RE5/AD13/ P1C	RE5	0	O	DIG	LATE<5> data output.
		1	I	ST	PORTE<5> data input.
	AD13(3)	x	O	DIG	External memory interface, address/data bit 13 output.(2)
		x	I	TTL	External memory interface, data bit 13 input.(2)
	P1C(1)	0	O	DIG	ECCP1 Enhanced PWM output, Channel C; takes priority over port and PSP data. May be configured for tri-state during Enhanced PWM shutdown events.

Legend: PWR = Power Supply, O = Output, I = Input, ANA = Analog Signal, DIG = Digital Output, ST = Schmitt Buffer Input, TTL = TTL Buffer Input, x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

Note 1: Default assignments for P1B/P1C and P3B/P3C when ECCPMX Configuration bit is set (80-pin devices only).

2: External memory interface I/O takes priority over all other digital and PSP I/O.

3: Available on 80-pin devices only.

4: Alternate assignment for ECCP2/P2A when the CCP2MX Configuration bit is cleared (all devices in Microcontroller mode).

NOTES:

FIGURE 19-13: I²C™ SLAVE MODE TIMING (TRANSMISSION, 10-BIT ADDRESSING)

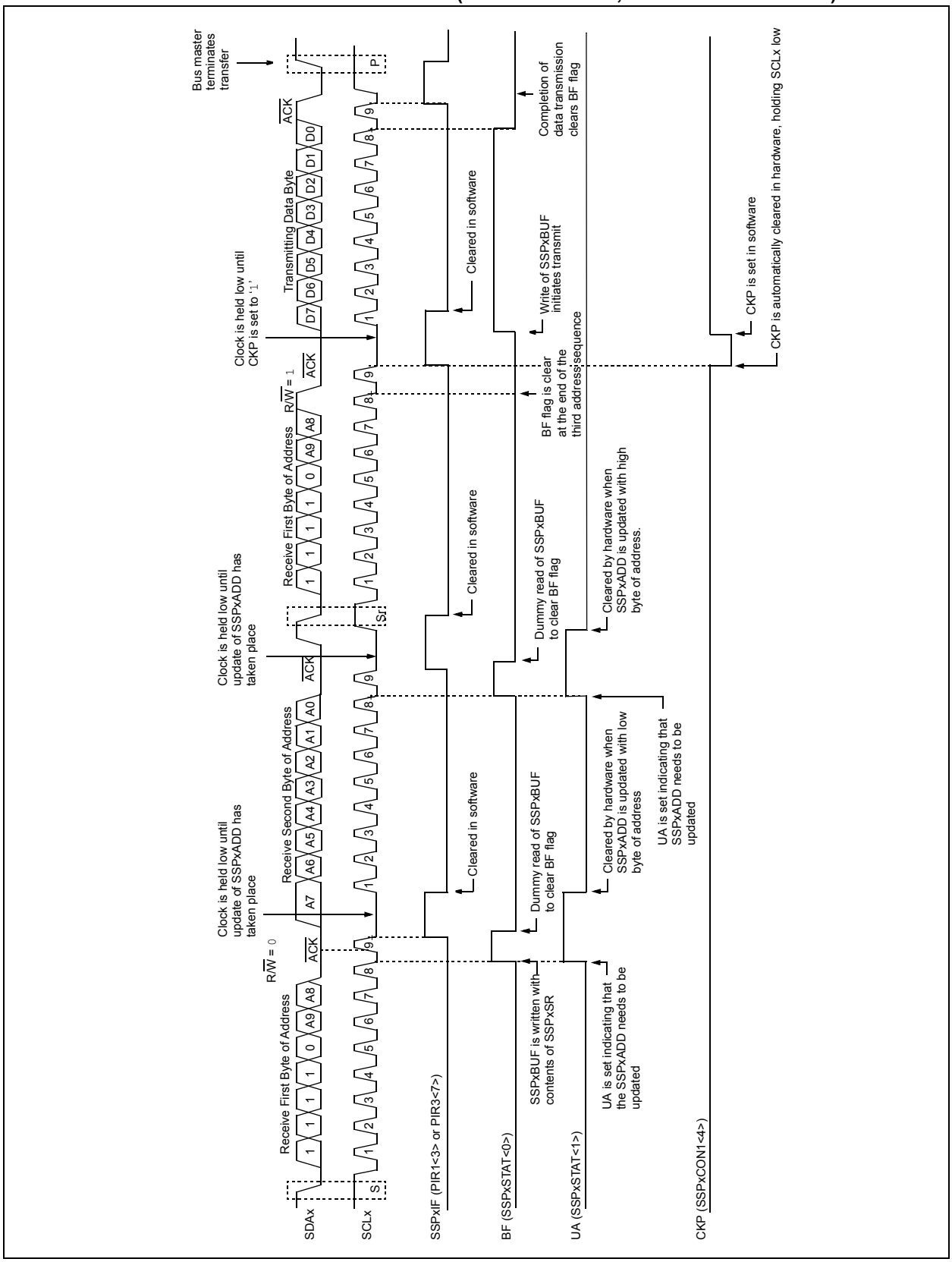


FIGURE 19-29: BUS COLLISION DURING START CONDITION (SCLx = 0)

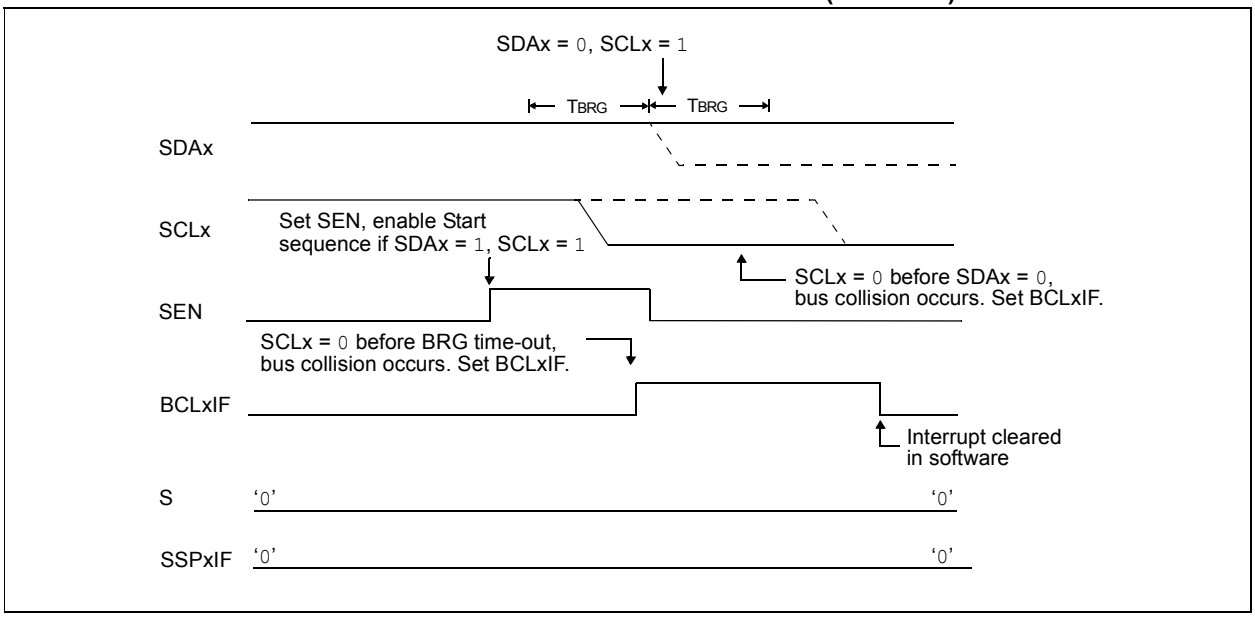
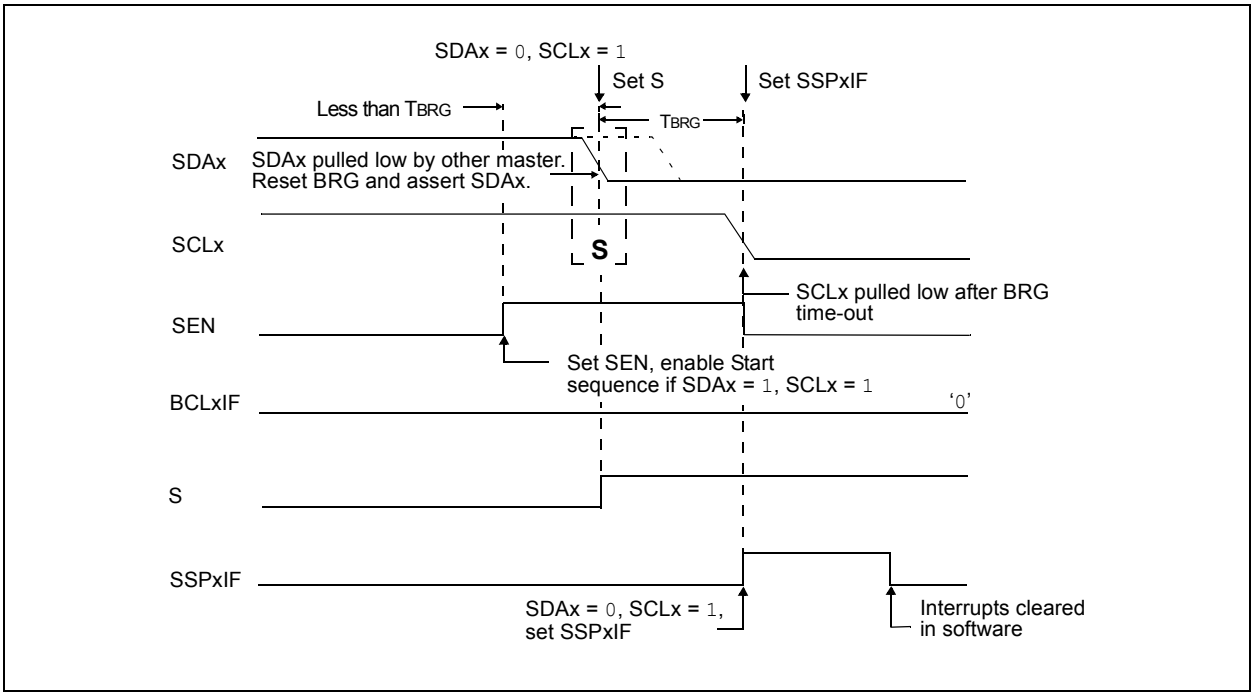


FIGURE 19-30: BRG RESET DUE TO SDAx ARBITRATION DURING START CONDITION



20.2.4.1 Special Considerations Using Auto-Wake-up

Since auto-wake-up functions by sensing rising edge transitions on RXx/DTx, information with any state changes before the Stop bit may signal a false end-of-character and cause data or framing errors. To work properly, therefore, the initial character in the transmission must be all '0's. This can be 00h (8 bytes) for standard RS-232 devices or 000h (12 bits) for LIN bus.

Oscillator start-up time must also be considered, especially in applications using oscillators with longer start-up intervals (i.e., HS or HSPLL mode). The Sync Break (or Wake-up Signal) character must be of sufficient length and be followed by a sufficient interval to allow enough time for the selected oscillator to start and provide proper initialization of the EUSART.

20.2.4.2 Special Considerations Using the WUE Bit

The timing of WUE and RCxIF events may cause some confusion when it comes to determining the validity of received data. As noted, setting the WUE bit places the EUSART in an Idle mode. The wake-up event causes a receive interrupt by setting the RCxIF bit. The WUE bit is cleared after this when a rising edge is seen on RXx/DTx. The interrupt condition is then cleared by reading the RCREGx register. Ordinarily, the data in RCREGx will be dummy data and should be discarded.

The fact that the WUE bit has been cleared (or is still set) and the RCxIF flag is set should not be used as an indicator of the integrity of the data in RCREGx. Users should consider implementing a parallel method in firmware to verify received data integrity.

To assure that no actual data is lost, check the RCIDL bit to verify that a receive operation is not in process. If a receive operation is not occurring, the WUE bit may then be set just prior to entering the Sleep mode.

FIGURE 20-8: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING NORMAL OPERATION

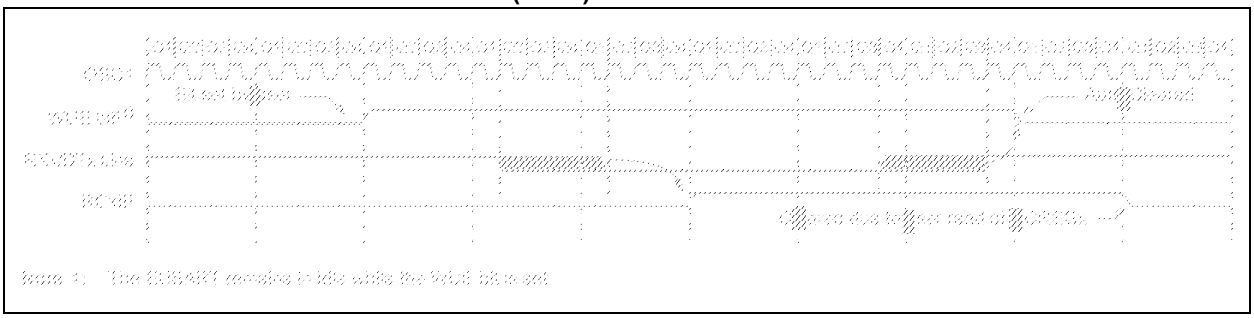


FIGURE 20-9: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING SLEEP

21.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) Converter module has 11 inputs for the 64-pin devices and 15 for the 80-pin devices. This module allows conversion of an analog input signal to a corresponding 10-bit digital number.

The module has five registers:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)
- A/D Control Register 2 (ADCON2)

The ADCON0 register, shown in Register 21-1, controls the operation of the A/D module. The ADCON1 register, shown in Register 21-2, configures the functions of the port pins. The ADCON2 register, shown in Register 21-3, configures the A/D clock source, programmed acquisition time and justification.

REGISTER 21-1: ADCON0: A/D CONTROL REGISTER 0

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCAL	—	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **ADCAL:** A/D Calibration bit
1 = Calibration is performed on next A/D conversion
0 = Normal A/D Converter operation (no calibration is performed)

bit 6 **Unimplemented:** Read as '0'

bit 5-2 **CHS<3:0>:** Analog Channel Select bits
0000 = Channel 0 (AN0)
0001 = Channel 1 (AN1)
0010 = Channel 2 (AN2)
0011 = Channel 3 (AN3)
0100 = Channel 4 (AN4)
0101 = Unused
0110 = Channel 6 (AN6)
0111 = Channel 7 (AN7)
1000 = Channel 8 (AN8)
1001 = Channel 9 (AN9)
1010 = Channel 10 (AN10)
1011 = Channel 11 (AN11)
1100 = Channel 12 (AN12)**(1,2)**
1101 = Unimplemented**(1,2)**
1110 = Unimplemented**(1,2)**
1111 = Unimplemented**(1,2)**

bit 1 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit
When ADON = 1:
1 = A/D conversion in progress
0 = A/D Idle

bit 0 **ADON:** A/D On bit
1 = A/D converter module is enabled
0 = A/D converter module is disabled

Note 1: These channels are not implemented on 64-pin devices.
2: Performing a conversion on unimplemented channels will return random values.

NOTES:

REGISTER 24-7: DEVID1: DEVICE ID REGISTER 1 FOR PIC18F87J10 FAMILY DEVICES

R	R	R	R	R	R	R	R
DEV2(1)	DEV1(1)	DEV0(1)	REV4	REV3	REV2	REV1	REV0
bit 7							bit 0

Legend:	
R = Read-only bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed	u = Unchanged from programmed state

bit 7-5 **DEV<2:0>:** Device ID bits(1)
111 = PIC18F85J10
101 = PIC18F67J10
100 = PIC18F66J15
011 = PIC18F66J10 or PIC18F87J10
010 = PIC18F65J15 or PIC18F86J15
001 = PIC18F65J10 or PIC18F86J10
000 = PIC18F85J15

bit 4-0 **REV<4:0>:** Revision ID bits
These bits are used to indicate the device revision.

Note 1: Where values for DEV<2:0> are shared by more than one device number, the specific device is always identified by using the entire DEV<10:0> bit sequence.

REGISTER 24-8: DEVID2: DEVICE ID REGISTER 2 FOR PIC18F87J10 FAMILY DEVICES

R	R	R	R	R	R	R	R
DEV10(1)	DEV9(1)	DEV8(1)	DEV7(1)	DEV6(1)	DEV5(1)	DEV4(1)	DEV3(1)
bit 7							bit 0

Legend:	
R = Read-only bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed	u = Unchanged from programmed state

bit 7-0 **DEV<10:3>:** Device ID bits(1)
These bits are used with the DEV<2:0> bits in the Device ID Register 1 to identify the part number.
0001 0101 = PIC18F65J10/65J15/66J10/66J15/67J10/85J10 devices
0001 0111 = PIC18F85J15/86J10/86J15/87J10 devices

Note 1: The values for DEV<10:3> may be shared with other device families. The specific device is always identified by using the entire DEV<10:0> bit sequence.

TSTFSZ **Test f, Skip if 0**

Syntax: TSTFSZ f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: skip if f = 0

Status Affected: None

Encoding:

0110	011a	ffff	ffff

Description: If 'f' = 0, the next instruction fetched during the current instruction execution is discarded and a NOP is executed, making this a two-cycle instruction.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    TSTFSZ  CNT, 1
NZERO   :
ZERO    :
```
Before Instruction
PC = Address (HERE)
After Instruction
If CNT = 00h,
PC = Address (ZERO)
If CNT ≠ 00h,
PC = Address (NZERO)

XORLW **Exclusive OR Literal with W**

Syntax: XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. $k \rightarrow W$

Status Affected: N, Z

Encoding:

0000	1010	kkkk	kkkk

Description: The contents of W are XORed with the 8-bit literal 'k'. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example:
```
XORLW   0AFh
```
Before Instruction
W = B5h
After Instruction
W = 1Ah

27.3 DC Characteristics: PIC18F87J10 Family (Industrial) (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial			
Param No.	**Symbol**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
	IPU	**Weak Pull-up Current**				
D070	IPURB	PORTB Weak Pull-up Current	30	240	μA	VDD = 3.3V, VPIN = VSS
	VOL	**Output Low Voltage**				
D080		I/O Ports (PORTB, PORTC)	—	0.4	V	IOL = 8.5 mA, VDD 3.3V
		I/O Ports (PORTD, PORTE, PORTJ)	—	0.4	V	IOL = 3.4 mA, VDD 3.3V
		I/O Ports (PORTA, PORTF, PORTG, PORTH)	—	0.4	V	IOL = 3.4 mA, VDD 3.3V
D083		OSC2/CLKO (EC, ECIO modes)	—	0.4	V	IOL = 1.0 mA, VDD 3.3V
	VOH	**Output High Voltage(3)**				
D090		I/O Ports (PORTB, PORTC)	2.4	—	V	IOL = -6 mA, VDD 3.3V
		I/O Ports (PORTD, PORTE, PORTJ)	2.4	—	V	IOL = -2 mA, VDD 3.3V
		I/O Ports (PORTA, PORTF, PORTG, PORTH)	2.4	—	V	IOL = -2 mA, VDD 3.3V
D092		OSC2/CLKO (EC, ECIO modes)	2.4	—	V	IOL = 1 mA, VDD 3.3V
		Capacitive Loading Specs on Output Pins				
D100(4)	COSC2	OSC2 Pin	—	15	pF	In HS mode when external clock is used to drive OSC1
D101	CIO	All I/O Pins	—	50	pF	To meet the AC Timing Specifications
D102	CB	SCLx, SDAx	—	400	pF	I^2C™ Specification

Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PIC® device be driven with an external clock while in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Refer to Table 11-2 for the pins that have corresponding tolerance limits.

27.4.3 TIMING DIAGRAMS AND SPECIFICATIONS

FIGURE 27-4: EXTERNAL CLOCK TIMING (ALL MODES EXCEPT PLL)

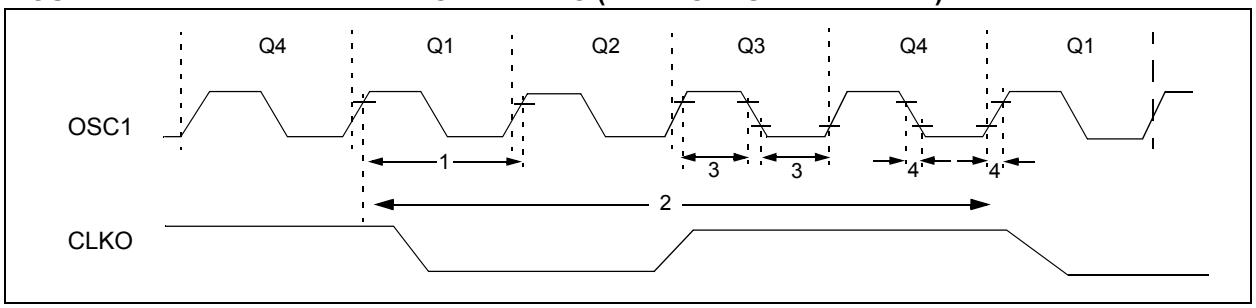


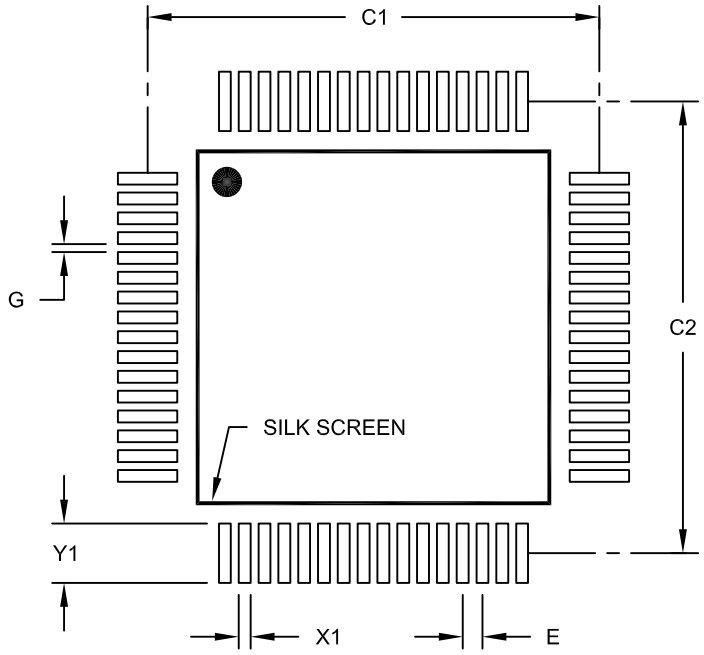
TABLE 27-6: EXTERNAL CLOCK TIMING REQUIREMENTS

Param. No.	Symbol	Characteristic	Min	Max	Units	Conditions
1A	FOSC	External CLKI Frequency(1)	DC	25	MHz	HS Oscillator mode
			DC	40	MHz	EC Oscillator mode
			DC	10	MHz	HSPLL, ECPLL Oscillator modes
		Oscillator Frequency(1)	4	25	MHz	HS Oscillator mode
			4	10	MHz	HS/EC + PLL Oscillator mode
1	TOSC	External CLKI Period(1)	40	—	ns	HS Oscillator mode
			25	—	ns	EC Oscillator mode
		Oscillator Period(1)	40	250	ns	HS Oscillator mode
			100	250	ns	HS/EC + PLL Oscillator mode
2	TCY	Instruction Cycle Time(1)	100	—	ns	TCY = 4/FOSC, Industrial
3	TOSL, TOSH	External Clock in (OSC1) High or Low Time	10	—	ns	HS Oscillator mode
4	TOSR, TOSF	External Clock in (OSC1) Rise or Fall Time	—	7.5	ns	HS Oscillator mode

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period for all configurations except PLL. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the “max.” cycle time limit is “DC” (no clock) for all devices.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085A

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